SPN4392W N-Channel Enhancement Mode MOSFET

DESCRIPTION

The SPN4392W is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application, notebook computer power management and other battery powered circuits where high-side switching.

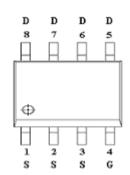
FEATURES

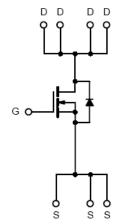
- 30V/13A, RDS(ON)= $8m\Omega$ @VGS=10V
- 30V/10A, RDS(ON)= $12m\Omega$ @VGS=4.5V
- Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- SOP 8P package design

APPLICATIONS

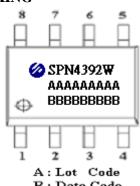
- Power Management in Note book
- Portable Equipment
- **Battery Powered System**
- High-Side DC/DC Converter
- Load Switch
- **DSC**
- LCD Display inverter

PIN CONFIGURATION(SOP – 8P)





PART MARKING



B: Date Code

PIN DESCRIPTION

Pin	Symbol	Description	
1	S	Source	
2	S	Source	
3	S	Source	
4	G	Gate	
5	D	Drain	
6	D	Drain	
7	D	Drain	
8	D	Drain	

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN4392WS8RGB	SOP- 8P	SPN4392W

[※] SPN4392WS8RGB: 13" Tape Reel; Pb − Free; Halogen - Free

ABSOULTE MAXIMUM RATINGS

(Ta=25°C Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		Vdss	30	V
Gate –Source Voltage		VGSS	±20	V
Continuous Drain Current(T _J =150°C)	TA=25°C	ID	13	A
Continuous Diani Current (13–130 C)	TA=70°C	ID	10	A
Pulsed Drain Current	Ірм	50	A	
Continuous Source Current(Diode Conduction)		Is	5.6	A
Doman Dissination	TA=25°C	- P _D	2.5	W
Power Dissipation	TA=70°C		1.6	W
Operating Junction Temperature		Тл	-55/150	$^{\circ}\mathbb{C}$
Storage Temperature Range		Tstg	-55/150	$^{\circ}\!\mathbb{C}$
Thermal Resistance-Junction to Ambient		R _θ JA	80	°C/W

ELECTRICAL CHARACTERISTICS

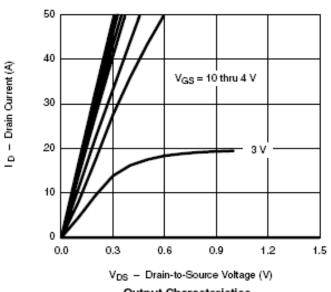
(TA=25°C Unless otherwise noted)

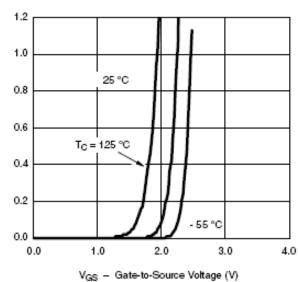
Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit		
Static								
Drain-Source Breakdown Voltage	V(BR)DSS	$V_{GS} = 0V$, $I_D = 250uA$	30			V		
Gate Threshold Voltage	VGS(th)	$V_{DS} = V_{GS}, I_{DS} = 250uA$	1.0		2.0	V		
Gate Leakage Current	Igss	$V_{DS} = 0V, V_{GS} = \pm 20 \text{ V}$			±100	nA		
		$V_{DS} = 24V, V_{GS} = 0V$			1			
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 24V, V_{GS} = 0V,$ $T_J = 55C$			100	uA		
Drain-Source On-Resistance	RDS(on)	$V_{GS} = 10V, ID = 13A$		0.006	0.008	Ω		
	$V_{GS} = 4.5V, ID$			0.009	0.012	2		
Forward Transconductance	gfs	$V_{DS} = 15V$, $I_{D} = 20 A$	10			S		
Diode Forward Voltage	Vsd	$I_F = 13 \text{ A}, V_{GS} = 0V$		1.0	1.5	V		
Dynamic								
Total Gate Charge	Qg	4.5		12	20	nC		
Gate-Source Charge	Qgs	$V_{DS} = 15V, V_{GS} = 5V,$ $I_{D} = 13 \text{ A}$		4				
Gate-Drain Charge	Qgd	1371		5] 		
Input Capacitance	Ciss			1500		pF		
Output Capacitance	Coss	$V_{GS} = 0V$, $V_{DS} = 25V$, F=1MHz		320				
Reverse Transfer Capacitance	Crss			200				
Turn-On Time	td(on)			8	12	ns		
	tr	$(V_{DD} = 15 \text{ V}, I_D = 13 \text{ A},$		10	15			
T 067 T	td(off)	$V_{GS}=10V,R_G=2.5\Omega)$		18	30			
Turn-Off Time	tf			6	9			

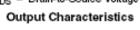
D - Drain Ourrent (A)

C – Capacitance (pF)

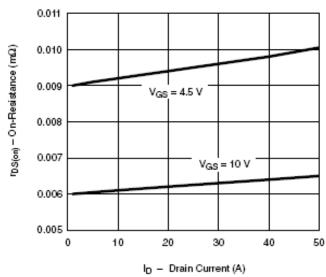
TYPICAL CHARACTERISTICS

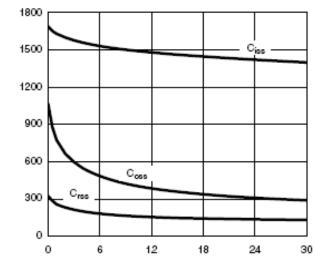








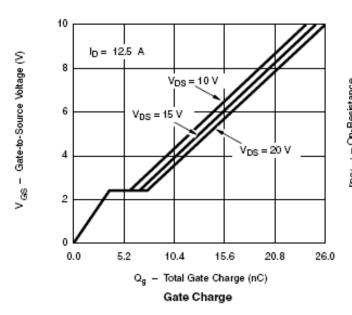


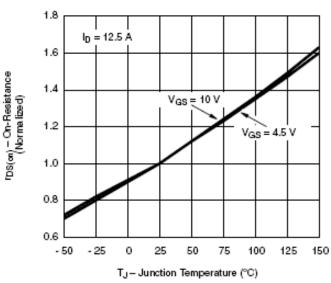


On-Resistance vs. Drain Current and Gate Voltage

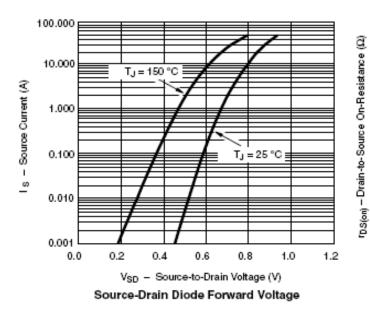
V_{DS} - Drain-to-Source Voltage (V) Capacitance

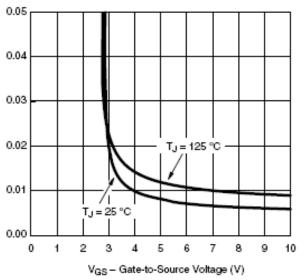
TYPICAL CHARACTERISTICS





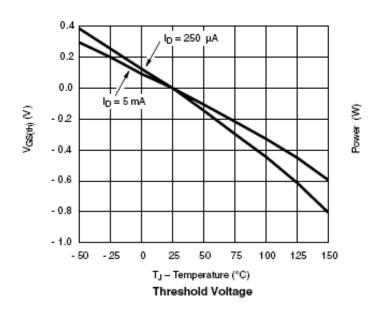


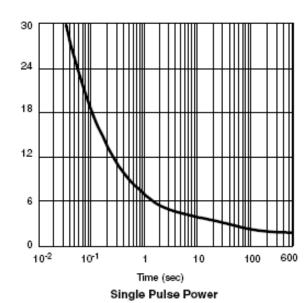


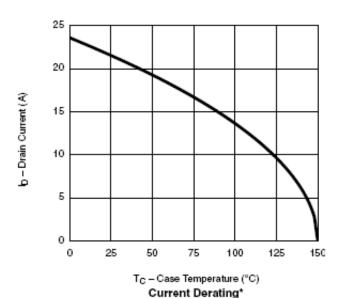


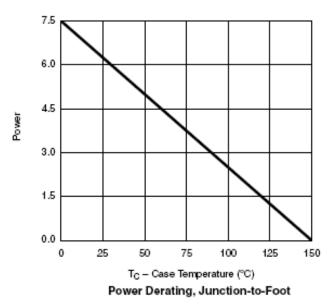
On-Resistance vs. Gate-to-Source Voltage

TYPICAL CHARACTERISTICS

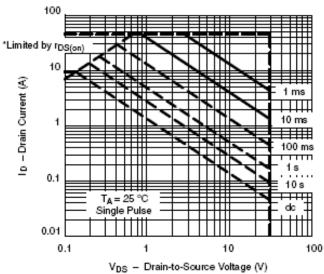








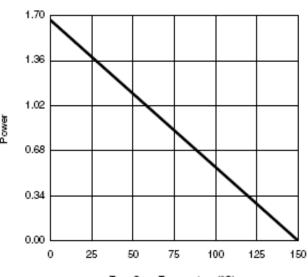
TYPICAL CHARACTERISTICS



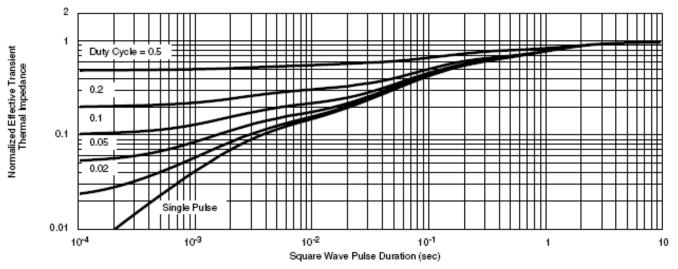
V_{DS} - Drain-to-Source Voltage (V)

*V_{GS} > minimum V_{GS} at which r_{DS(cn)} is specified

Safe Operating Area, Junction-to-Ambient



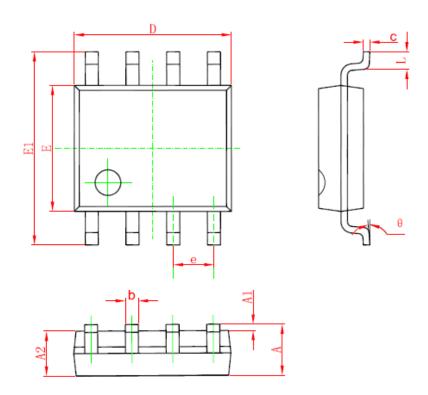
T_C – Case Temperature (°C)
Power, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



SOP- 8 PACKAGE OUTLINE



Combail	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
А	1. 350	1. 750	0.053	0.069	
A1	0. 100	0. 250	0.004	0.010	
A2	1. 350	1. 550	0.053	0.061	
b	0. 330	0. 510	0.013	0. 020	
С	0. 170	0. 250	0.006	0.010	
D	4. 700	5. 100	0. 185	0. 200	
E	3. 800	4. 000	0. 150	0. 157	
E1	5. 800	6. 200	0. 228	0. 244	
е	1. 270 (BSC)		0. 050 (BSC)		
L	0. 400	1. 270	0.016	0.050	
θ	0°	8°	0°	8°	

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